

TRENTO Workshop, March 2022

Magdalena Munker on behalf of the  
MONOLITH team.

# Picosecond time stamping in fully monolithic highly granular silicon pixel detectors

*funded by the H2020 ERC Advanced grant 884447*



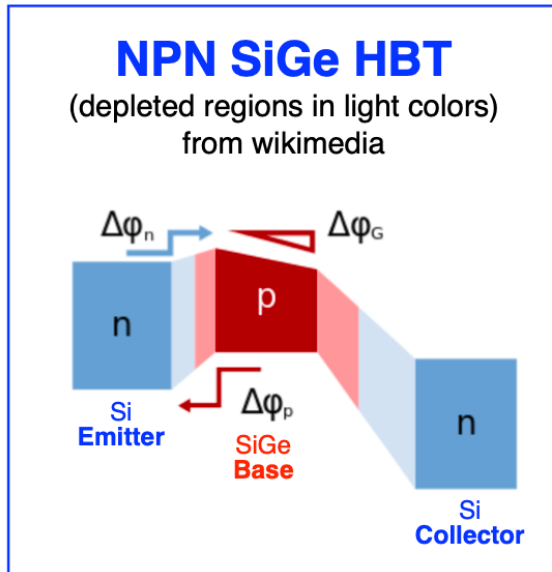
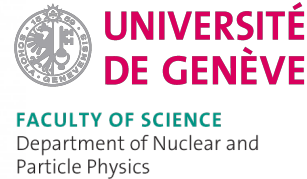
**UNIVERSITÉ  
DE GENÈVE**

**FACULTY OF SCIENCE**  
Department of Nuclear and  
Particle Physics



European Research Council  
Established by the European Commission

# SiGe BiCMOS front end technology



SiGe HBT = BJT with Germanium as base material:

- higher doping in base possible
- thinner base
- **reduced base resistance  $R_b$**

Grading of Ge doping in base:

- charge transport in base via drift
- reduced charge transit time in base
- **high current gain  $\beta$**

$$ENC_{series\ noise} \propto \sqrt{k_1 \frac{C_{tot}^2}{\beta} + k_2 R_b C_{tot}^2}$$

**Leading-edge technology IHP SG13G2, 130 nm process featuring SiGe HBT with:**

- Transistor transition frequency:  **$f_t = 0.3\ THz$**
- DC Current gain:  **$\beta = 900$**
- Delay gate: **1.8 ps**

- Implemented in silicon sensor
- Used for pre-amplifier and drivers




innovations  
for high  
performance  
microelectronics

Leibniz-Institut für  
innovative Mikroelektronik

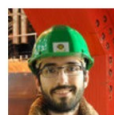
# The MONOLITH team at UniGe




**Giuseppe Iacobucci**  
• project P.I.  
• System design



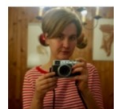
**Didier Ferrere**  
• System integration  
• Laboratory test



**Pierpaolo Valerio**  
• Lead chip design  
• Digital electronics




**Mateus Vicente**  
• System integration  
• Laboratory test



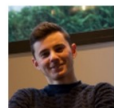
**Yana Gurimskaya**  
• Radiation tolerance  
• Laboratory test




**Stefano Zambito**  
• Laboratory test




**Stéphane Débieux**  
• Board design  
• RO system




**Théo Moretti**  
• Laboratory test



**Antonio Picardi**  
• Chip design  
• Laboratory Test




**Lorenzo Paolozzi**  
• Sensor design  
• Analog electronics



**Sergio Gonzalez-Sevilla**  
• System integration  
• Laboratory test




**Magdalena Munker**  
• Sensor design  
• Laboratory test



**Roberto Cardella**  
• Sensor design  
• Analog electronics



**Fulvio Martinelli**  
• Chip design



**Yannick Favre**  
• Board design  
• RO system



**Chiara Magliocca**  
• Laboratory test



**Matteo Milanese**  
• Laboratory test



**Jihad Said**  
• Laboratory test

## Main research partners:




**Roberto Cardarelli**  
INFN Rome Tor Vergata



**Marzio Nessi**  
CERN & UNIGE




**Ivan Peric**  
KIT



**Holger Rücker**  
IHP Mikroelektronik



**Mehmet Kaynak**  
IHP Mikroelektronik



**Bernd Heinemann**  
IHP Mikroelektronik

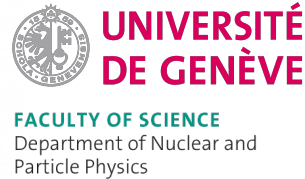
## Wide range of activities:

Chip design and simulation, sensor design and simulation, sensor + chip testing in probe station, climate chamber, test-beam,...

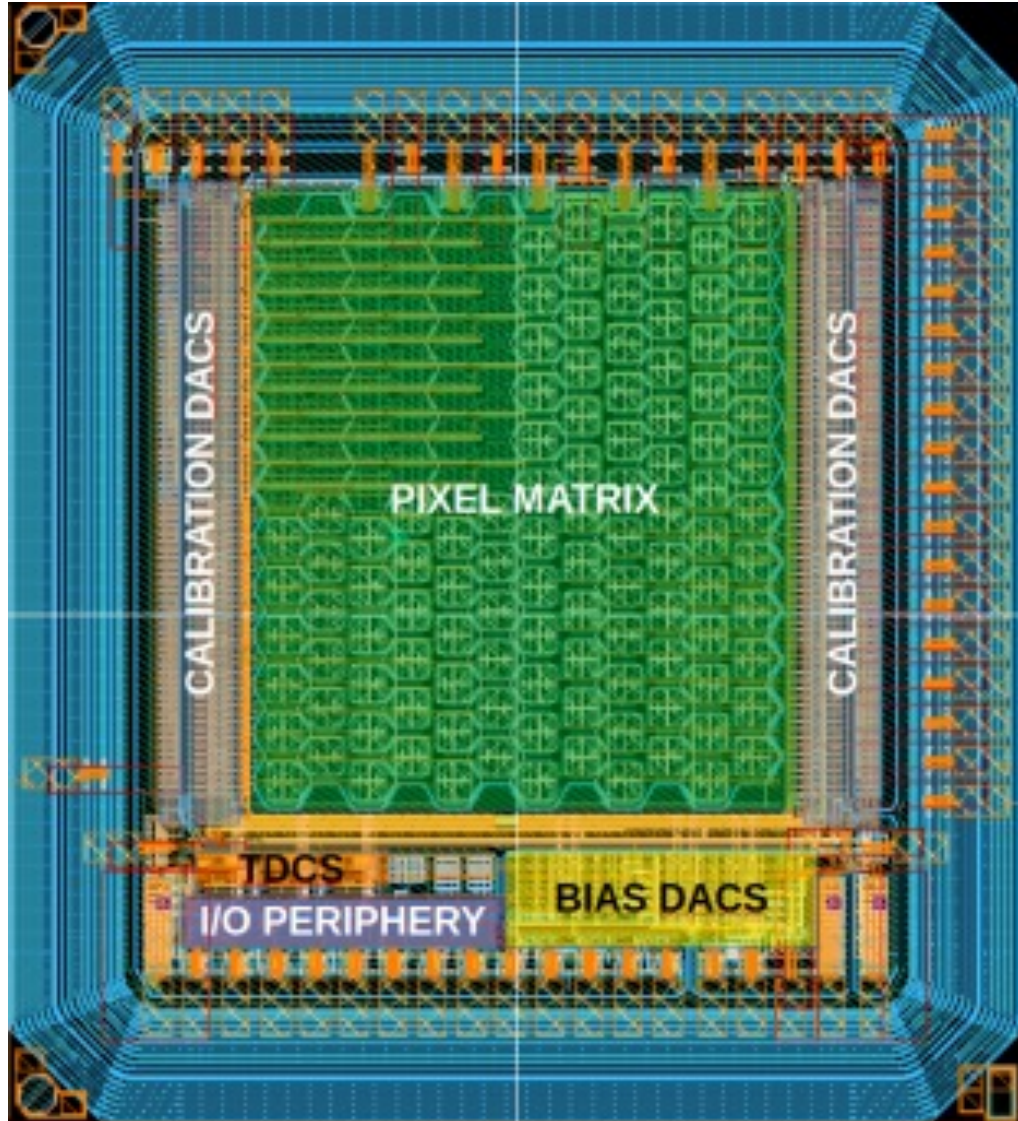
<https://www.unige.ch/dpnc/en/groups/giuseppe-iacobucci/research/monolith-erc-advanced-project/>



# The ATTRACT prototype



MPW submission in 2019 funded by H2020:



- **Hexagonal pixels with large collection electrode:**
  - Homogenous drift field
  - Reduced breakdown probability at pixel implant corners
- **100 $\mu$ m pitch**
- **25 $\mu$ m p-type epitaxial layer**

## Four Matrices:

### 1. Active pixel

- Front end in pixel
- HBT preamp + driver (in pixel) + CMOS discriminator (outside pixel)

### 2. Active pixel v2

- HBT preamp + CMOS discriminator

### 3. Limiting amplifier

- HBT preamp + HBT limiting amplifier

### 4. Double threshold

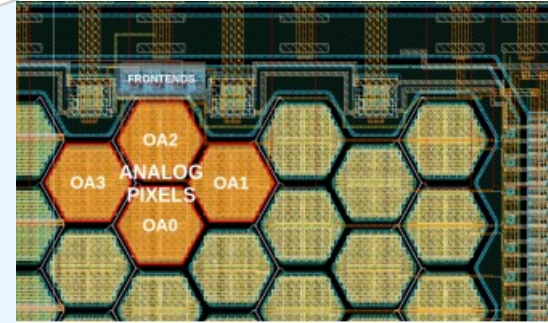
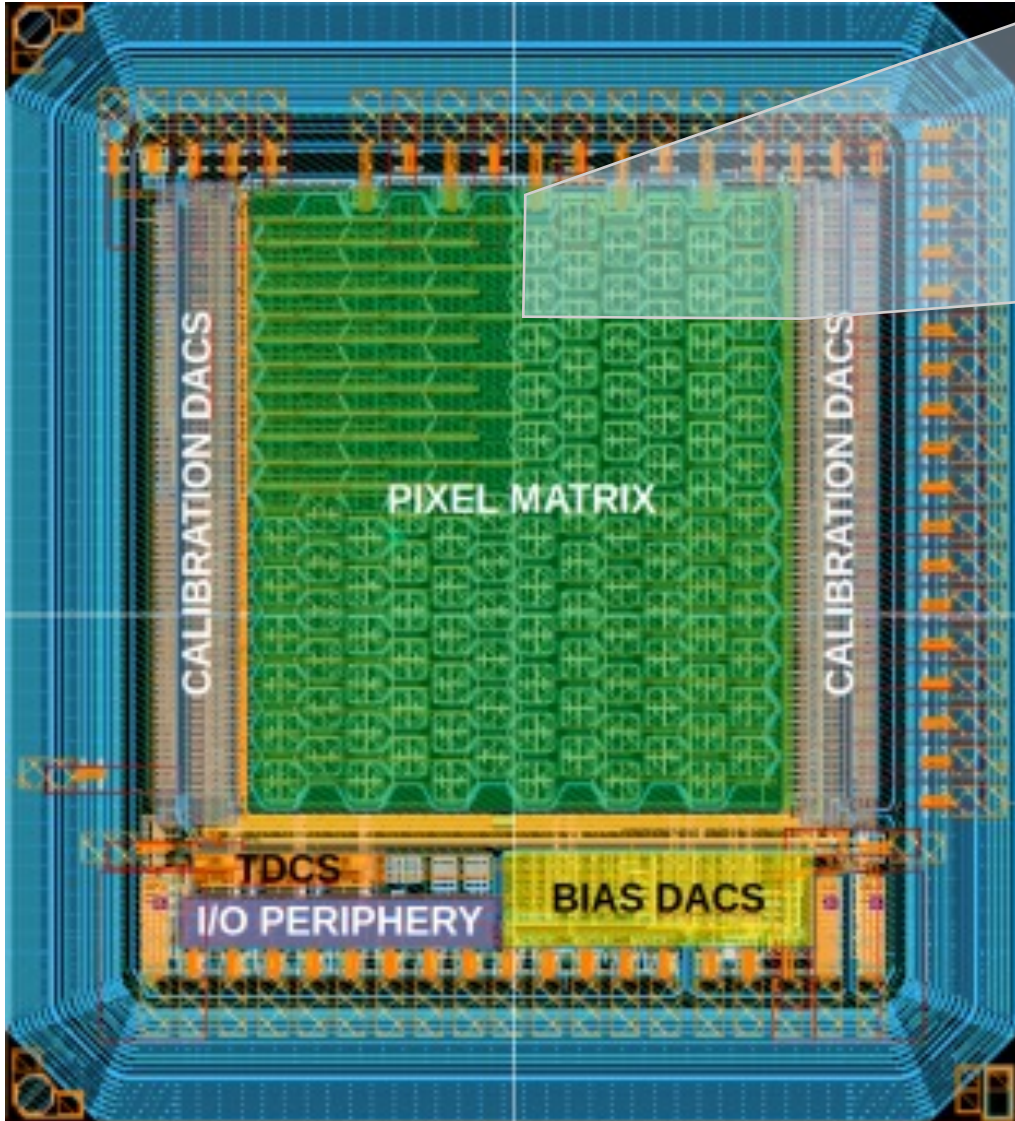
- HBT preamp + two CMOS discriminators



# Analogue pixels of the ATTRACT chip



MPW submission in 2019 funded by H2020:

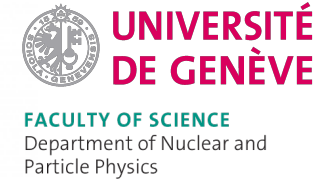


**4 analog channels include:**

HBT preamp + two HBT Emitter Followers to 500 $\Omega$   
Resistance on pad.

→ Test of **analogue channels** to investigate HBT and sensor performance

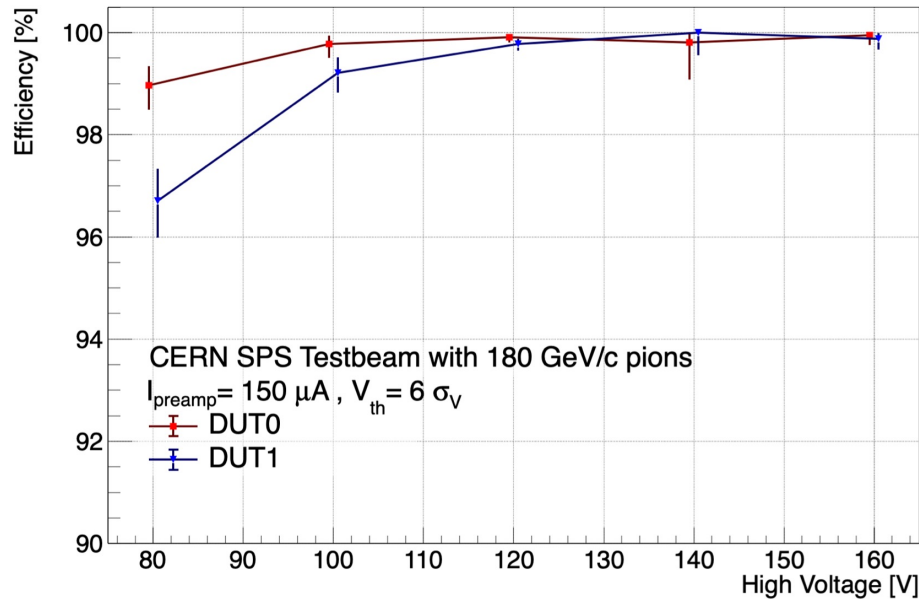
# Test beam results – performance for different sensor bias



CERN SPS 180GeV pion beam, FEI4 Telescope ( $\sigma_x \sim 10\mu m$   $\sigma_y \sim 15\mu m$ ), 2 DUTs for timing reference

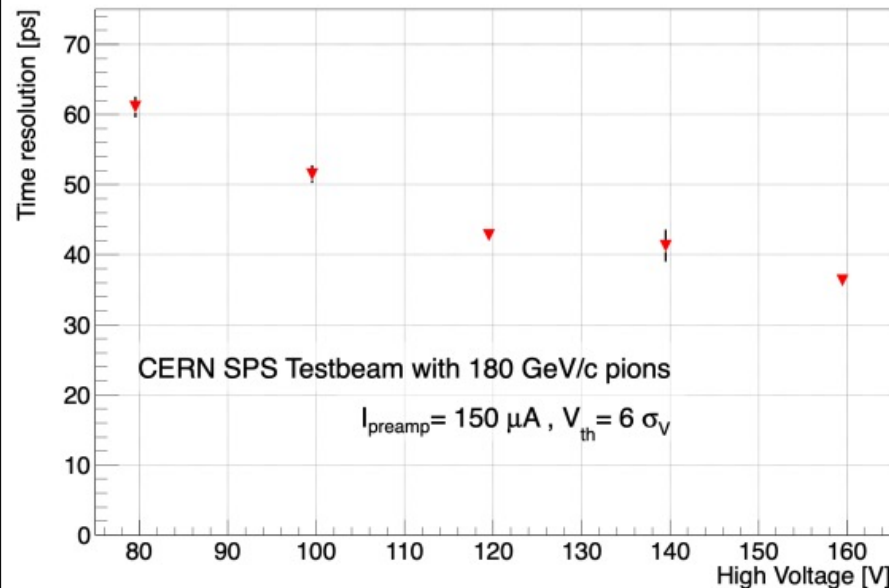
<https://doi.org/10.1088/1748-0221/17/02/P02019>

Efficiency as a function of high voltage:



- Large efficient operation range
- Differences of DUTs due to different threshold values

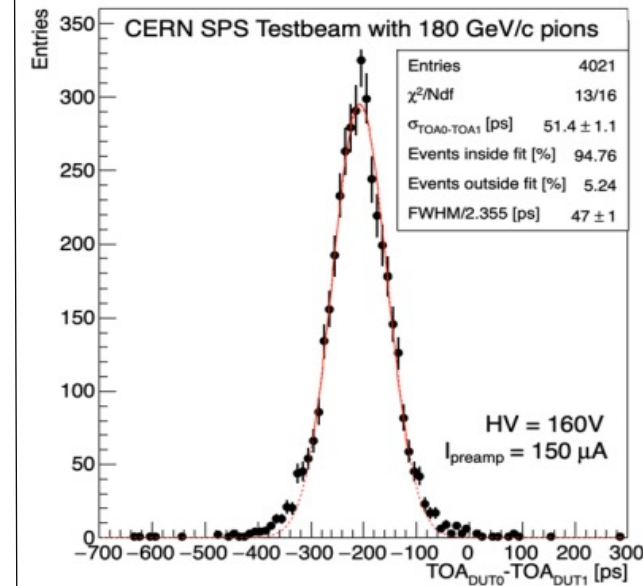
Time resolution as a function of high voltage:



$$\sigma_t = \frac{\sigma_{TOA0-TOA1}}{\sqrt{2}} = (36.4 \pm 0.8) \text{ps}$$

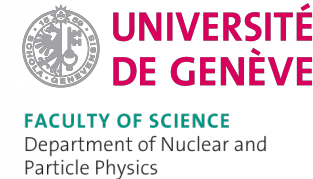
Without gain layer

Timing residual:



- Gaussian distribution of timing residual

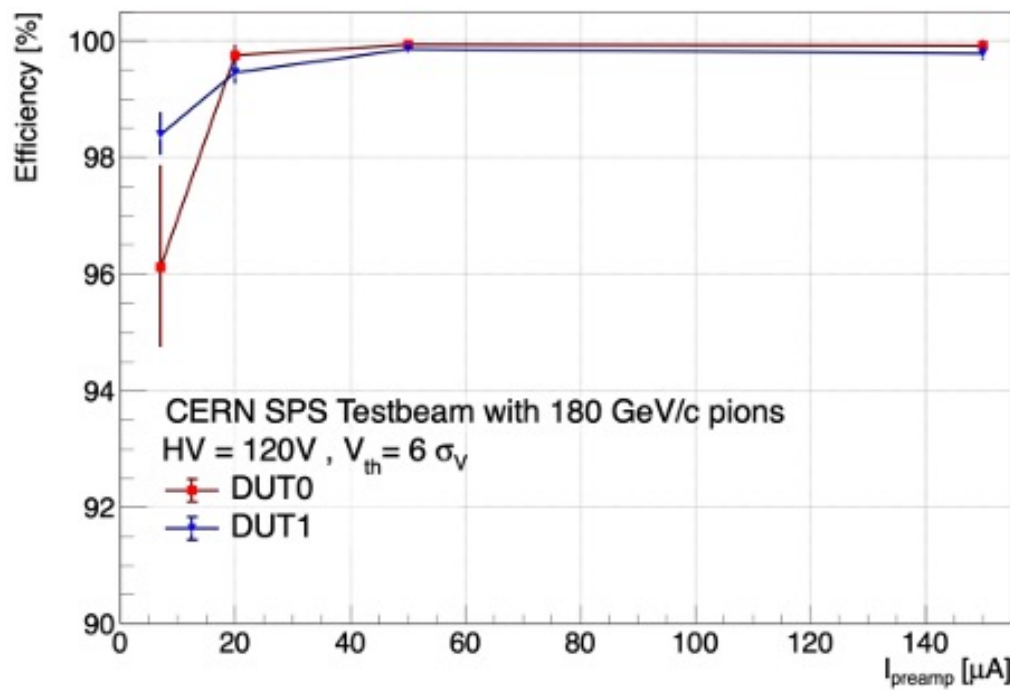
# Test beam results – performance for different pre-amp current



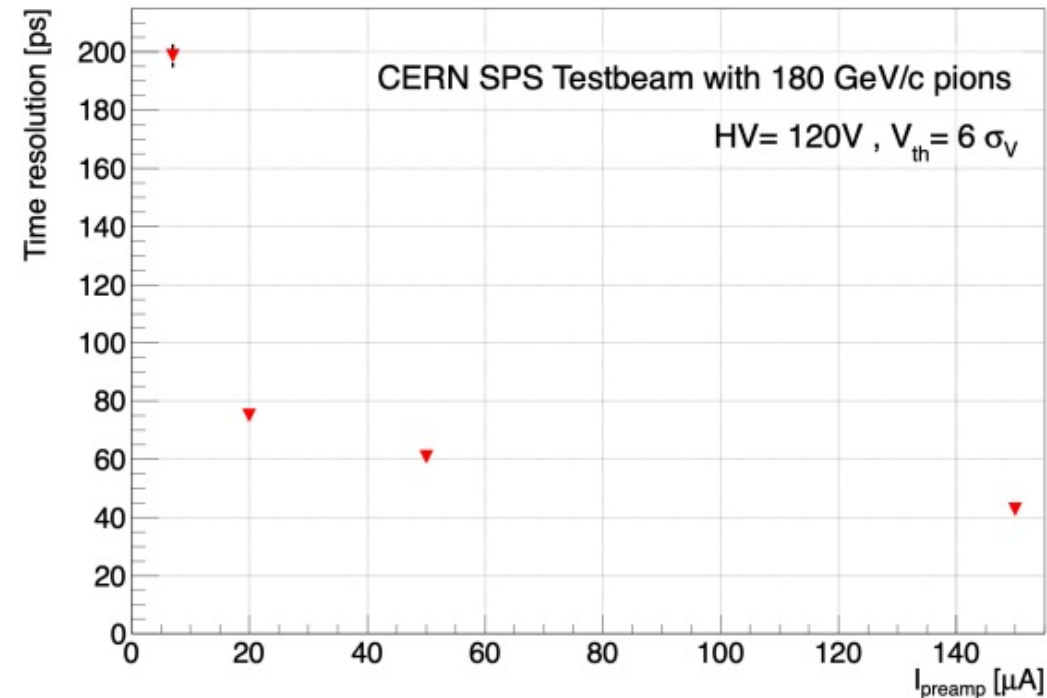
CERN SPS 180GeV pion beam, FEI4 Telescope ( $\sigma_x \sim 10\mu m$   $\sigma_y \sim 15\mu m$ ), 2 DUTs for timing reference

<https://doi.org/10.1088/1748-0221/17/02/P02019>

Efficiency as a function of preamplifier current:



Time resolution as a function of preamplifier current:



- Power consumption dominated by preamplifier current
- Efficiency > 99.5% and time resolution below 80ps even at low preamplifier current of 20 $\mu A$



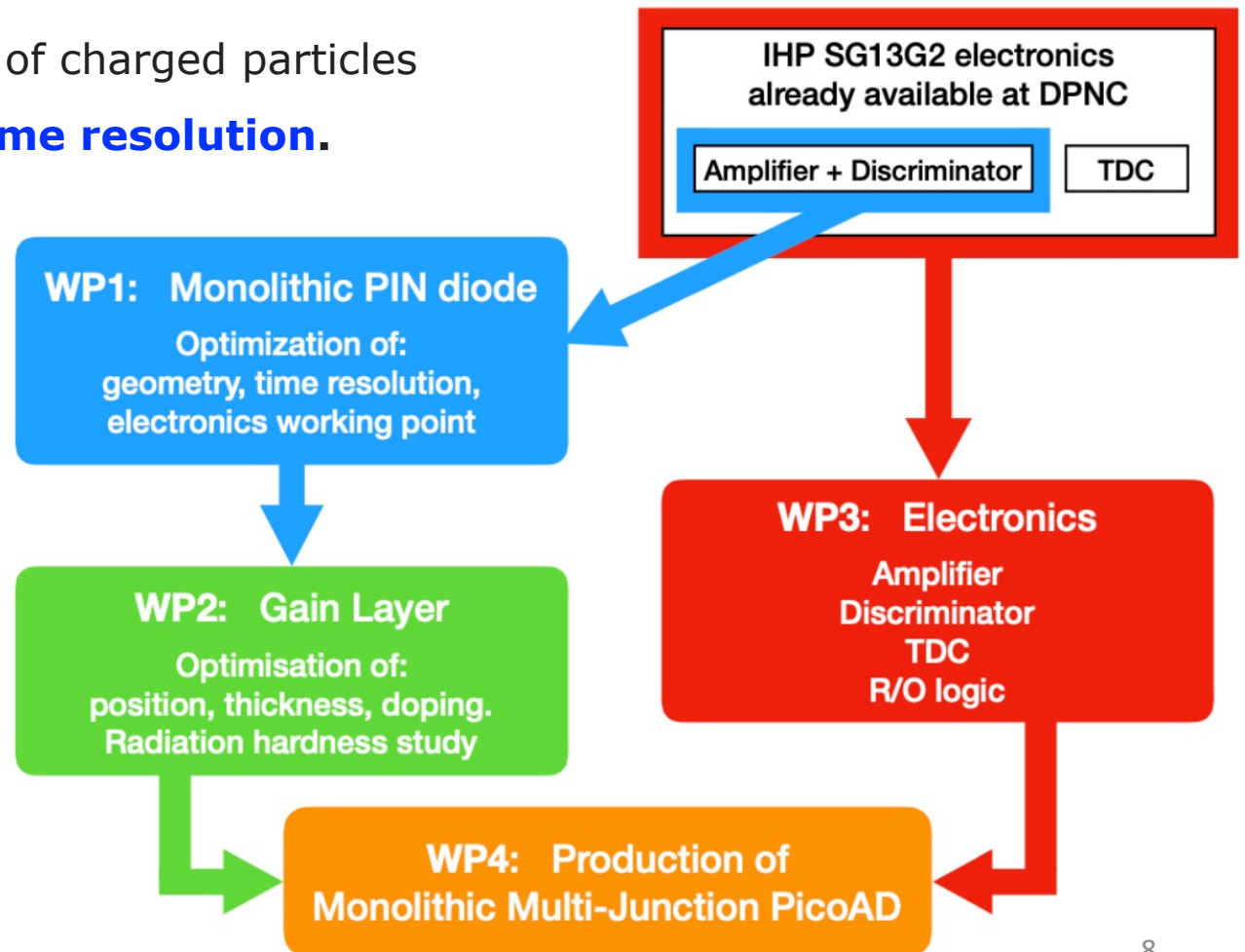
# The MONOLITH ERC Advanced Project

**5 year ERC project to develop:**

Monolithic silicon sensor

able to measure precisely the 3D spatial position of charged particles

while providing at the same time **picosecond time resolution.**



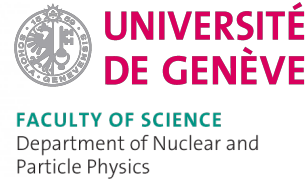
H2020 ERC Advanced grant 884447,  
 July 2020 - June 2025

<https://www.unige.ch/dpnc/en/groups/giuseppe-iacobucci/research/monolith-erc-advanced-project/>

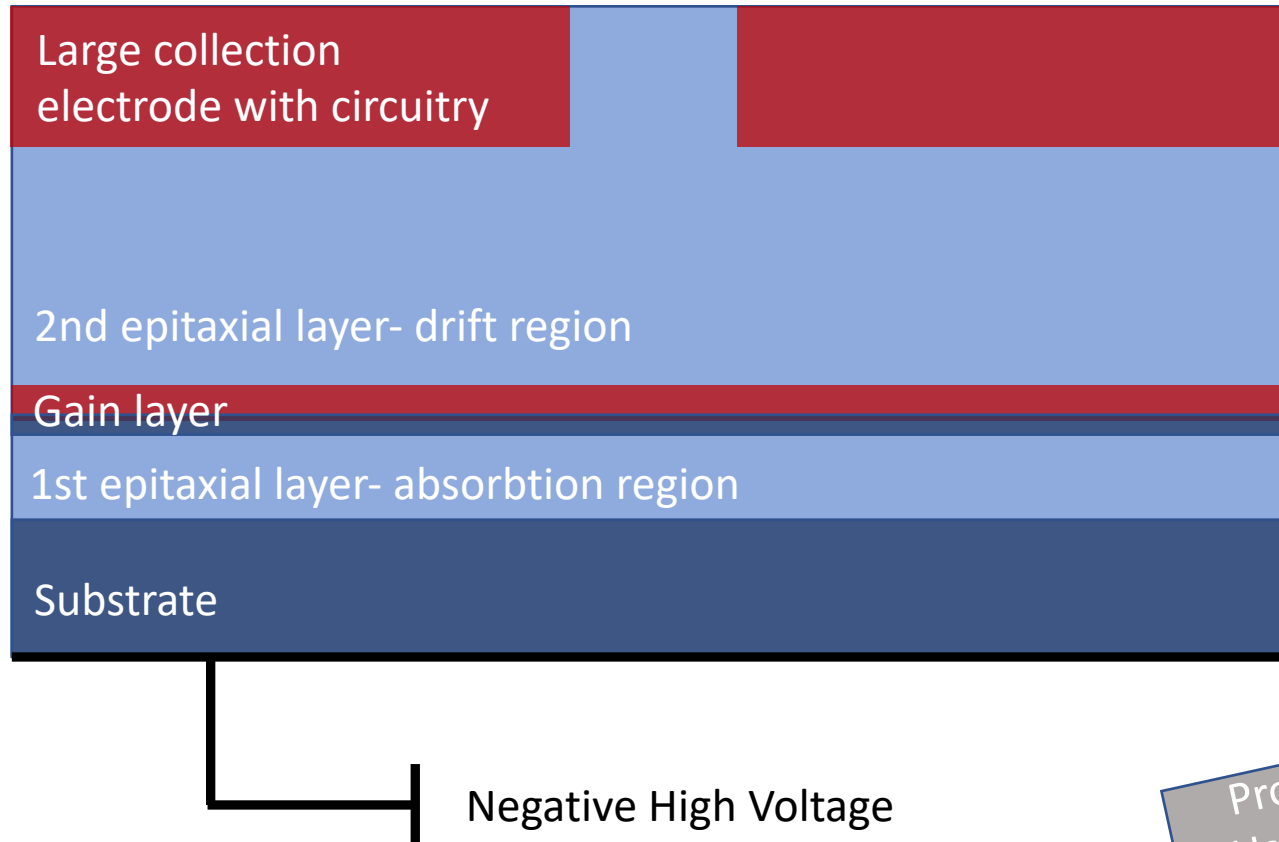


# PicoAD sensor concept

Picosecond Avalanche Detector (PicoAD): EU Patent EP18207008.6



## Schematic view of PicoAD sensor concept:

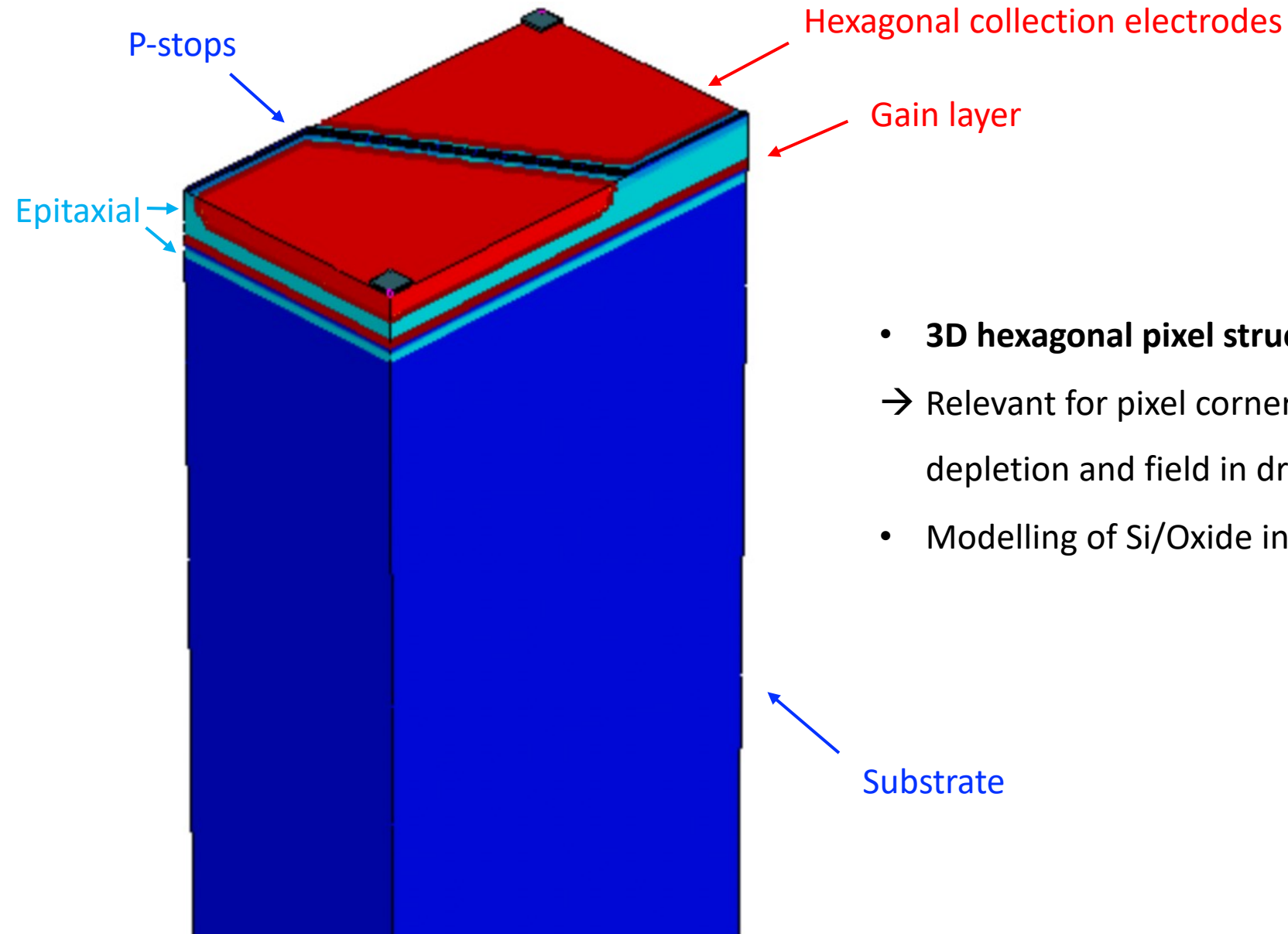
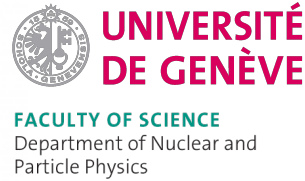


## Placement of gain layer deep inside sensor:

- De-correlation from pixel implant size/geometry  
→ High pixel granularity possible (*spatial precision*)
- Only small fraction of charge gets amplified  
→ Reduced charge fluctuations (*timing precision*)

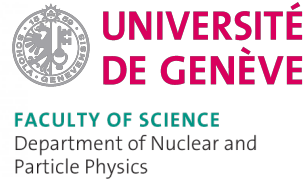
Produced with different doses and 15 $\mu$ m total epi  
Using the ATTRACT prototype electronics and pixel

# PicoAD – 3D TCAD structure

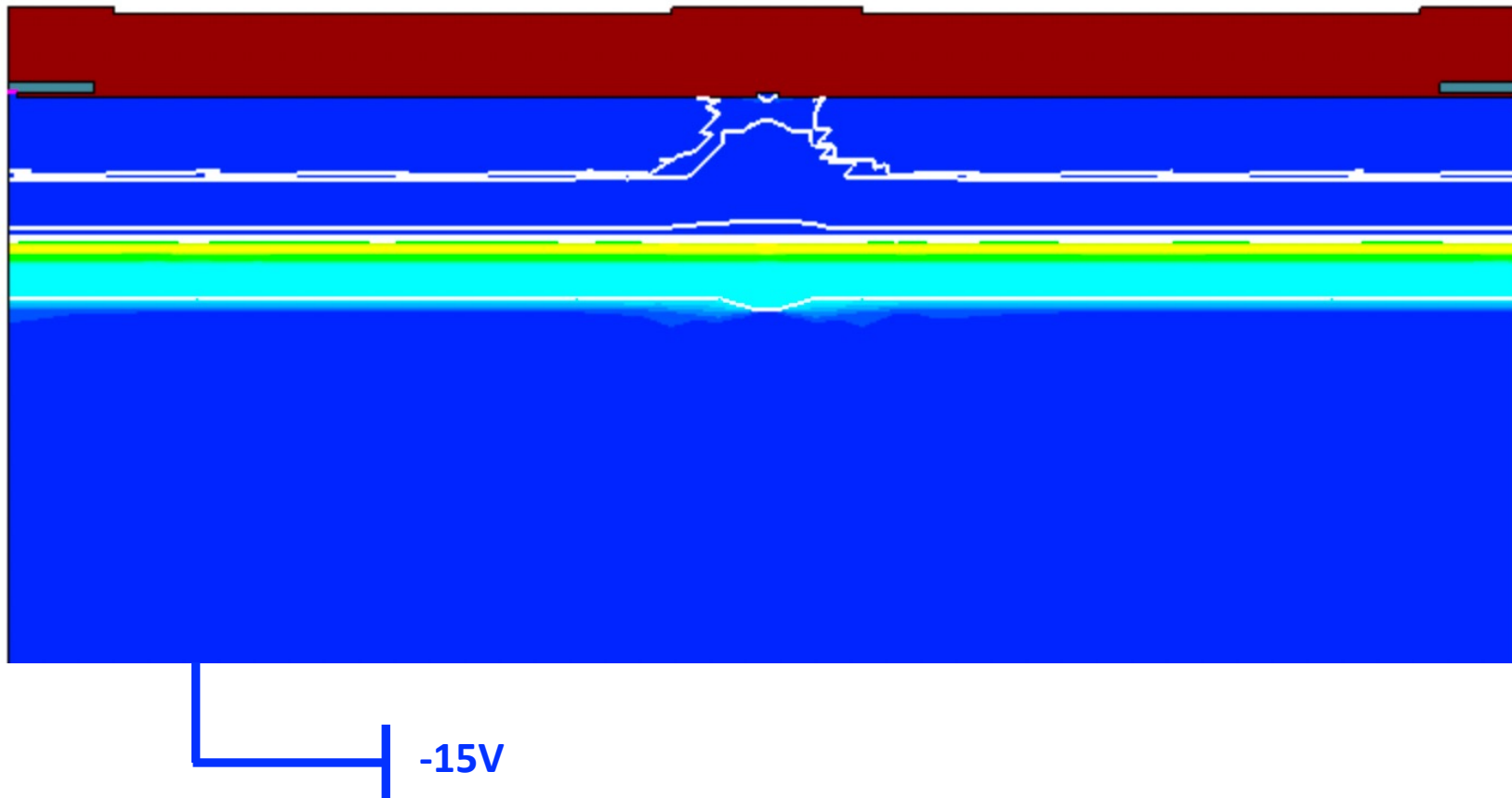


- **3D hexagonal pixel structure** of pixels in matrix  
→ Relevant for pixel corners, breakdown around p-stops and depletion and field in drift region
- Modelling of Si/Oxide interface (not presented here)

# PicoAD – 3D TCAD, electric field and depletion



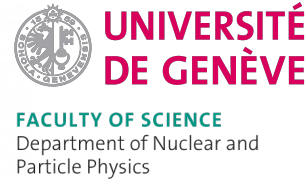
2D cross section of 3D TCAD, electric field (color scale) and depletion (white line):



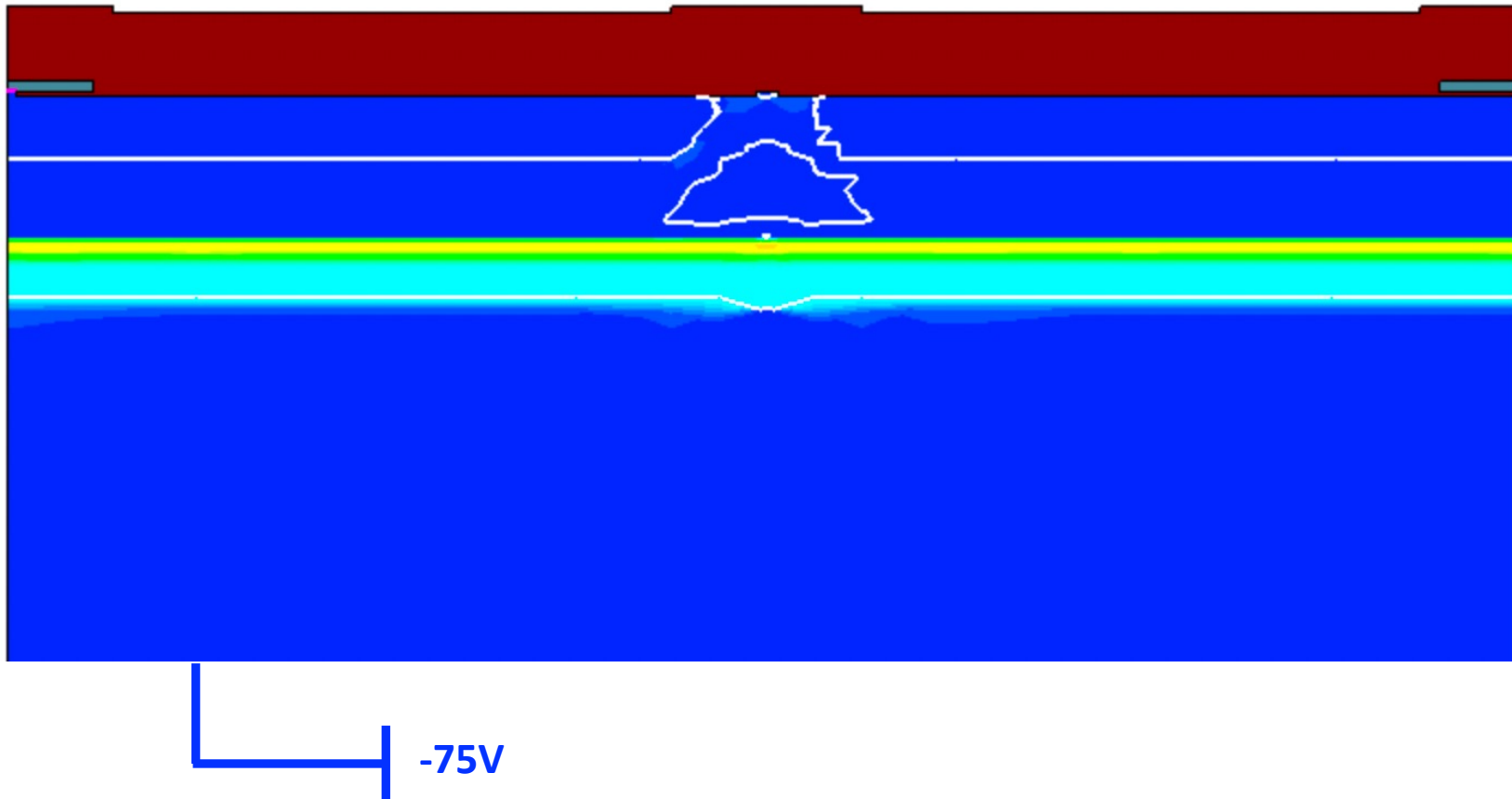
Depletion and electric field first build up in absorption layer, when applying voltage to the backside



# PicoAD – 3D TCAD, electric field and depletion



2D cross section of 3D TCAD, electric field (color scale) and depletion (white line):

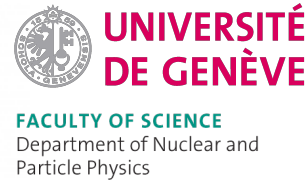


Electric field and depletion in drift layer start to build up after depletion of gain layer

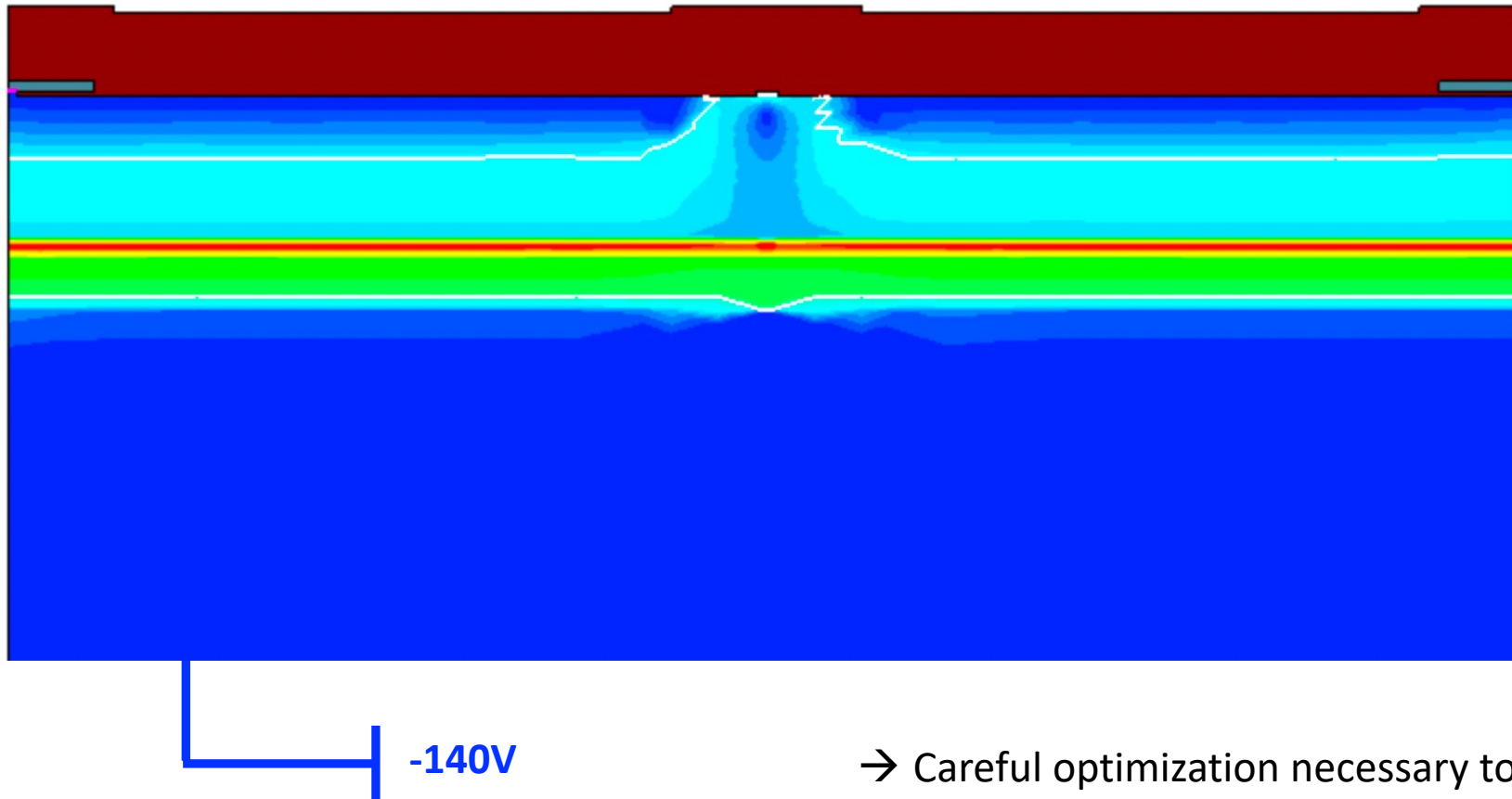
'Pockets' under p-stops in 2nd epitaxial layer deplete last

→ Relevance of 3D modelling and optimisation of inter-pixel region

# PicoAD – 3D TCAD, electric field and depletion



2D cross section of 3D TCAD, electric field (color scale) and depletion (white line):



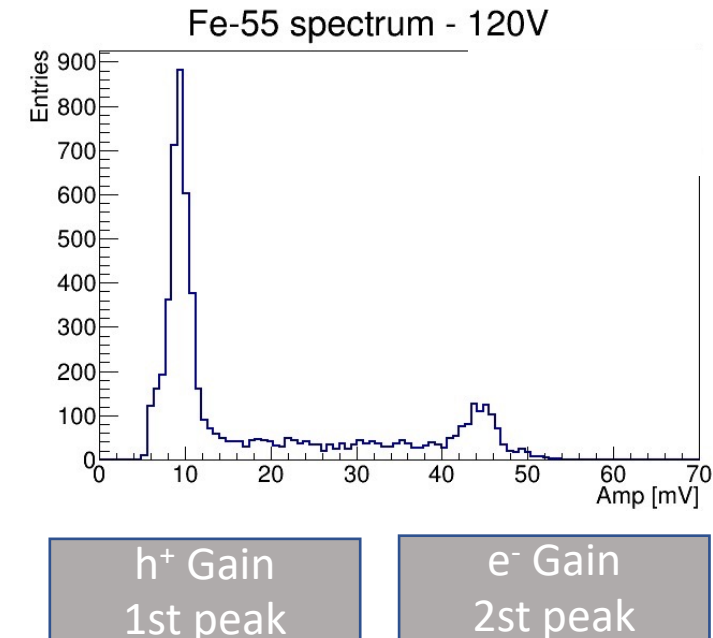
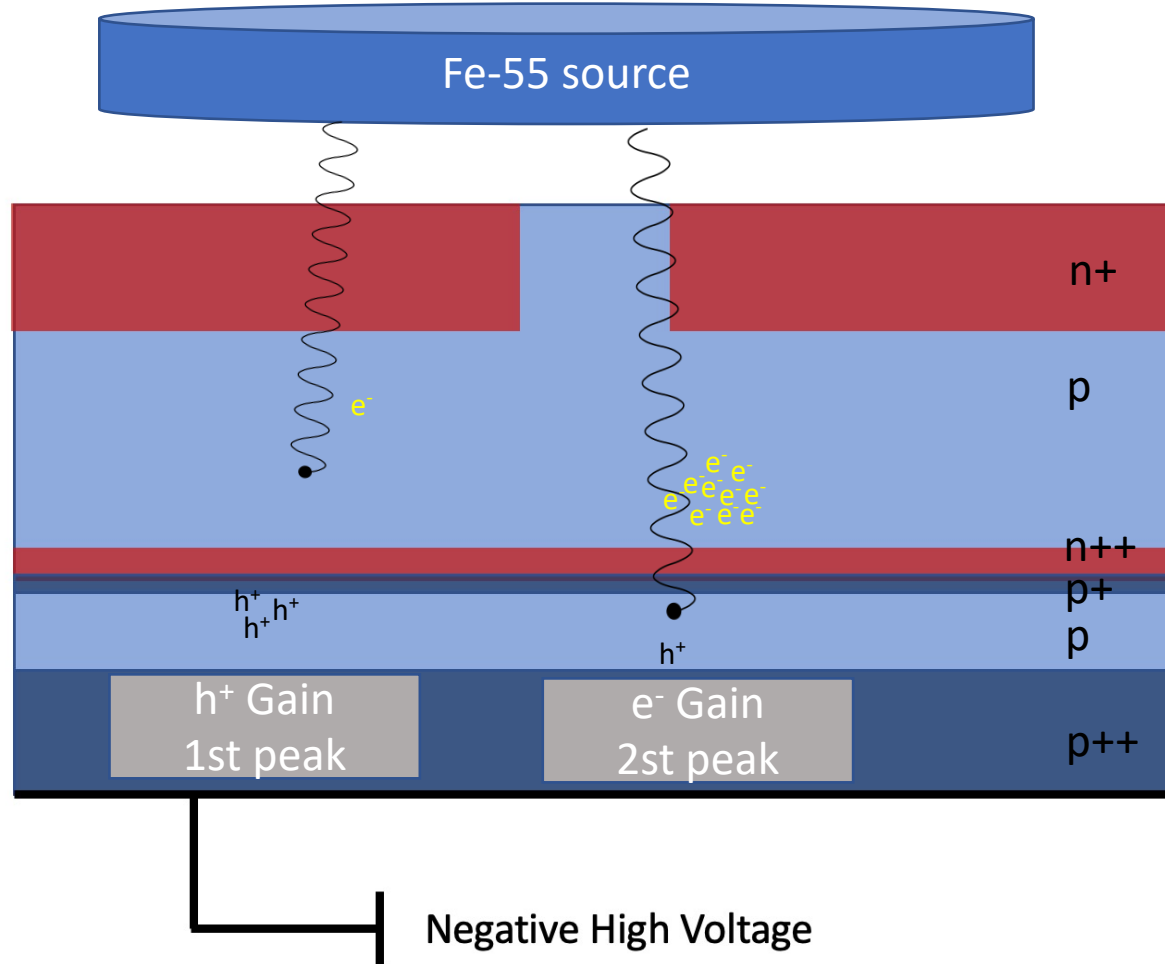
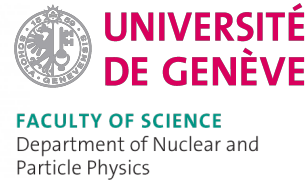
After full depletion the drift field in the 2nd epitaxial layer is build up

→ Important to saturate drift velocity

Planar field in drift and gain layer except for p-stop region

→ Careful optimization necessary to fully deplet and build up field in drift region while maintaining stable high field in gain layer.

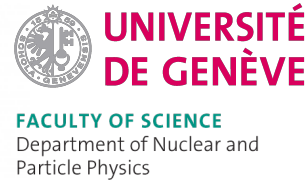
# 55-Fe measurement concept



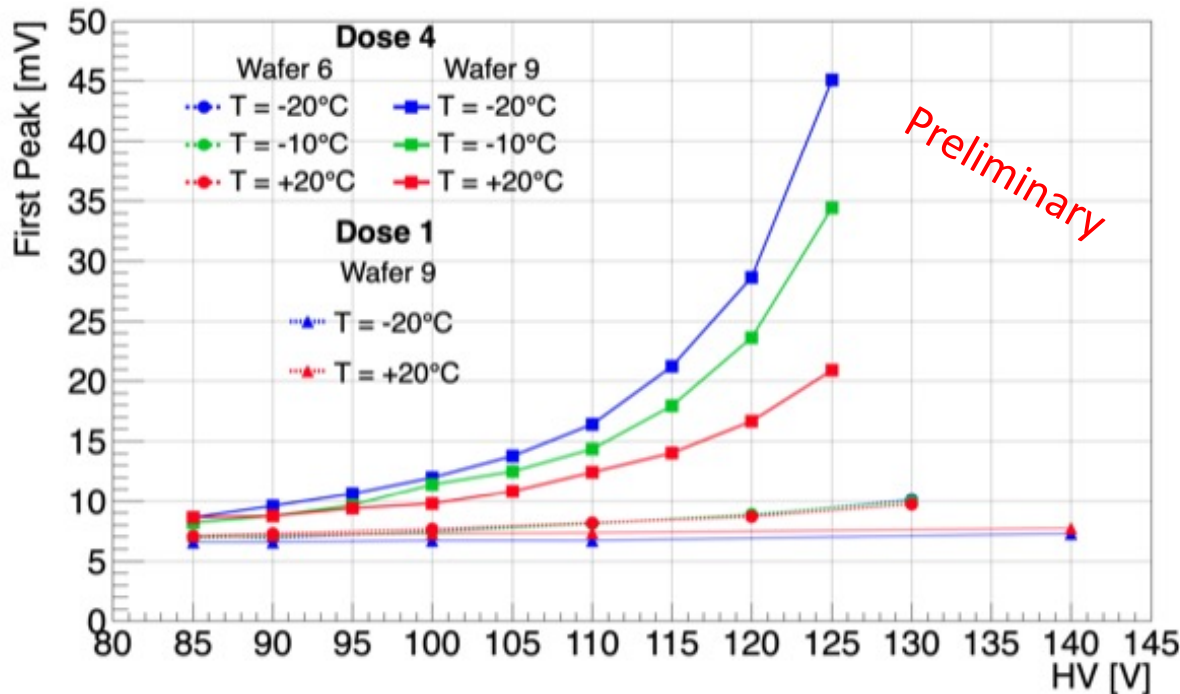
- Only carriers passing through the gain layer are multiplied
- Two different peaks for  $e^-$  and  $h^+$
- Measurements performed in climate chamber to investigate gain as a function of temperature



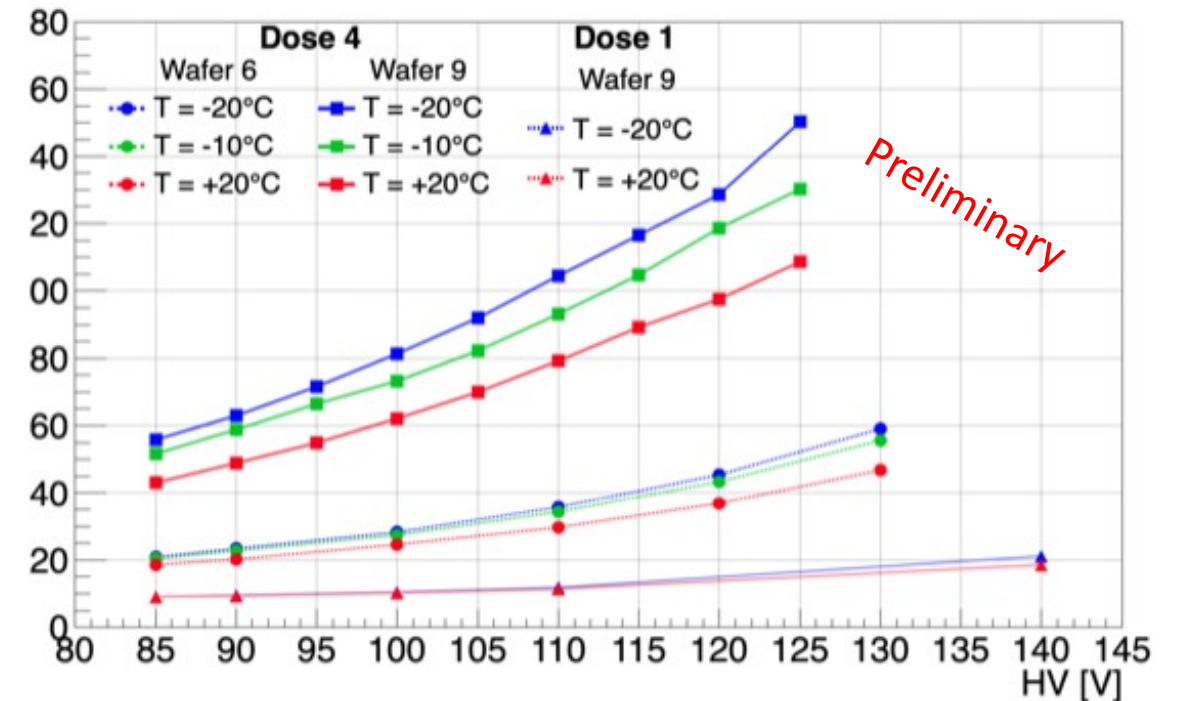
# 55-Fe climate chamber measurement results



First peak of the 55-Fe spectrum as a function of the High Voltage (HV):

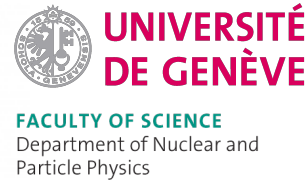


Second peak of the 55-Fe spectrum as a function of the High Voltage (HV):

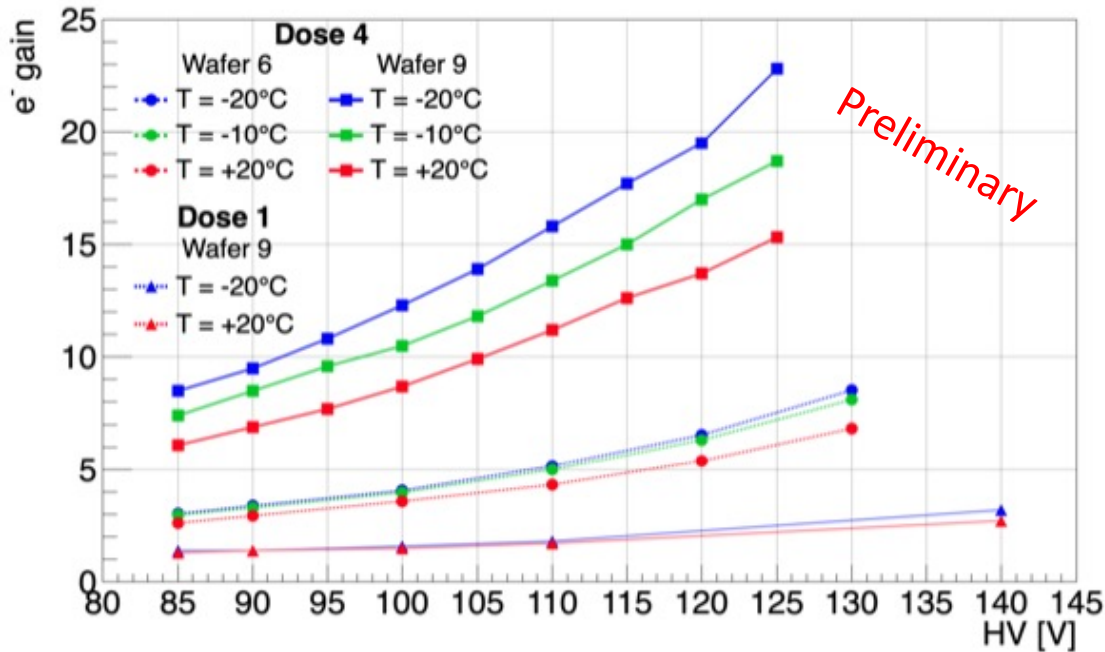


- Electron and hole gain increase with HV and temperature
- Clear difference between wafer 6 and wafer 9 for the same dose (under investigation)
- Lowest dose 1 shows almost no hole gain, used for normalization to get electron gain (next slide)

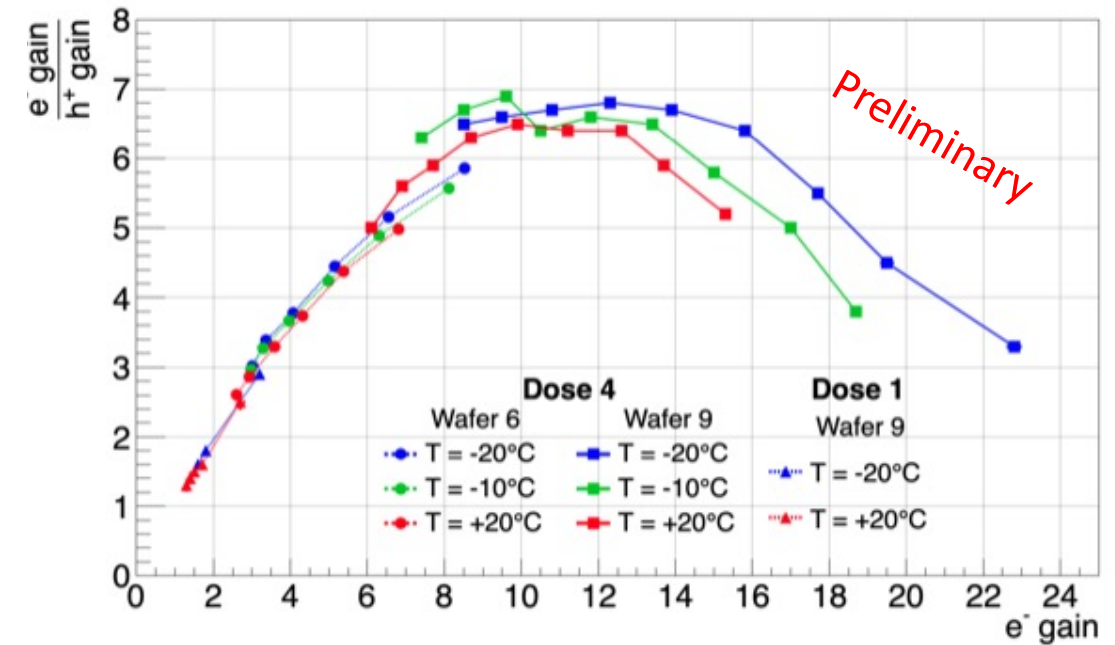
# 55-Fe climate chamber measurement results



e<sup>-</sup> gain vs HV



Gain ratio vs e<sup>-</sup> gain



- Gain up to above 20 for wafer 9
- Gain most likely underestimated due to space charge effects from high local charge from 55-Fe

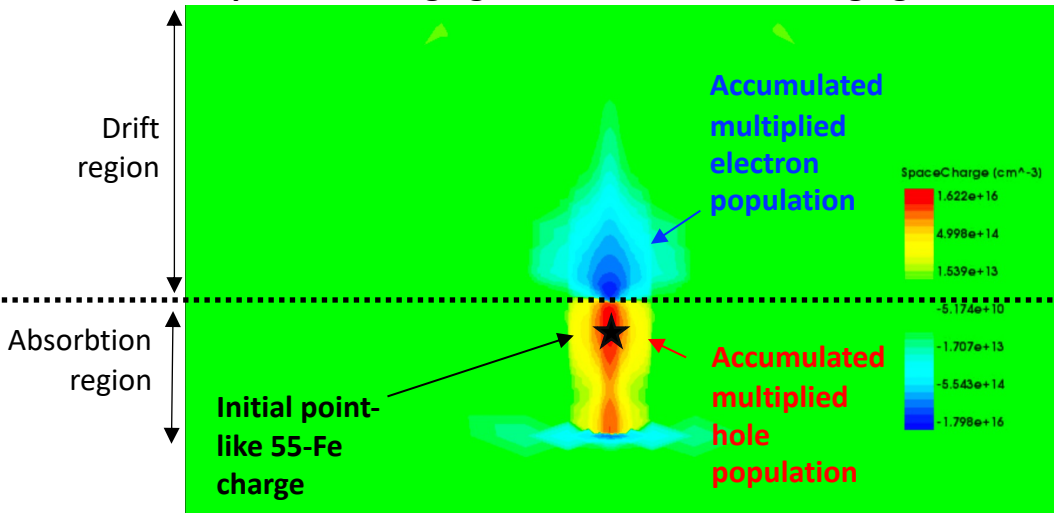
- Consistent behaviour of the 3 samples
- Ratio of e/h-gain decreased at higher e-gain values (expected to saturate)
- Possible explanation: space charge effects

# Space charge effects in picoAD double junction sensor

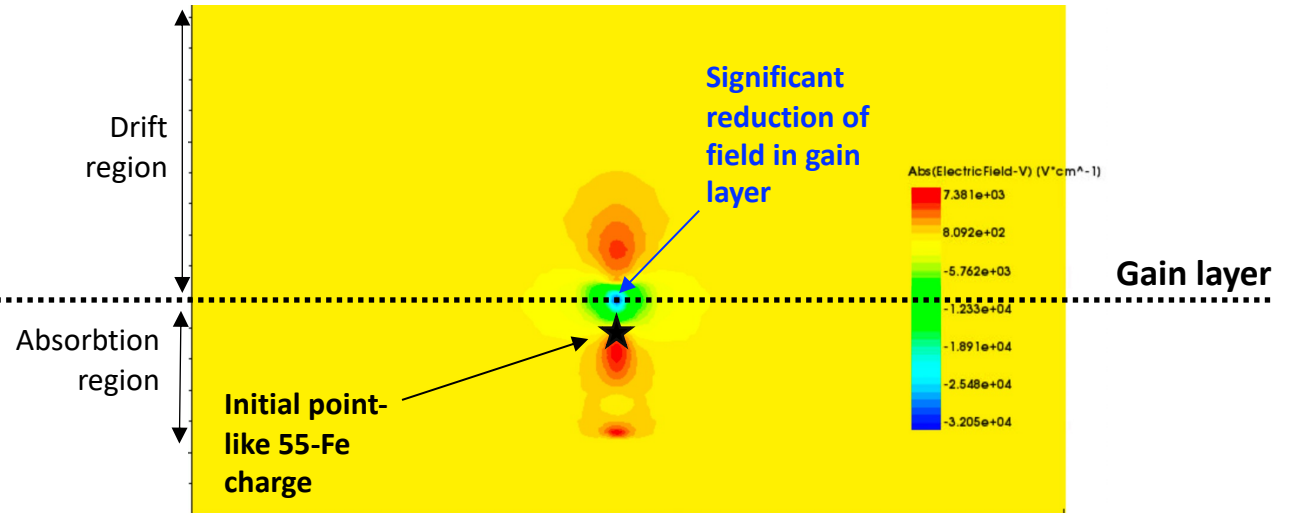
Transient 3D TCAD simulation of point like 55-Fe charge deposition in absorption layer:

Preliminary

**Space charge:**  
50ps after charge generation – before charge generation:



**Electric field:**  
50ps after charge generation – before charge generation



- Reduced e-gain for higher local charge densities (higher initial charges or higher field values in gain layer, resulting in larger number of multiplied charges)
- Transient field simulation necessary

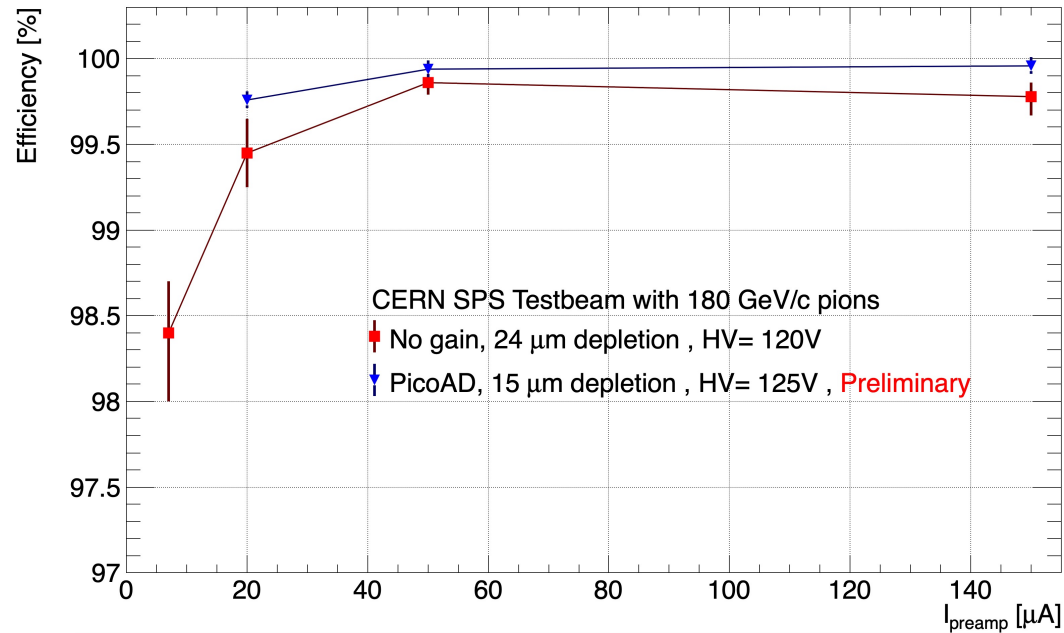


# Test beam results for PicoAD

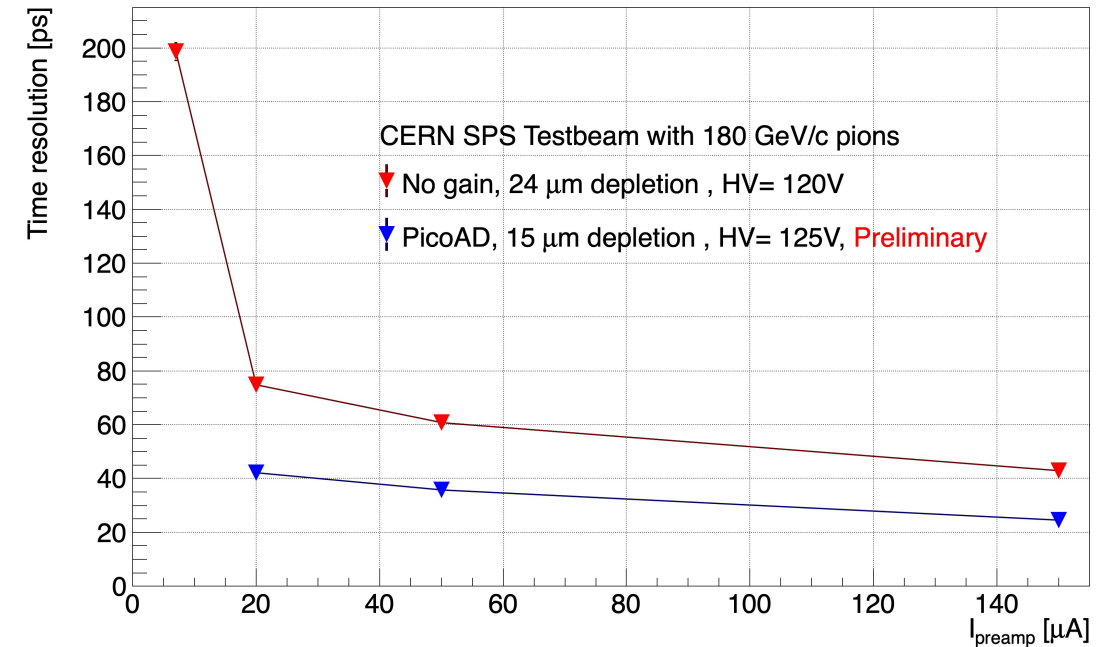
CERN SPS 180GeV pion beam, FEI4 Telescope ( $\sigma_x \sim 10\mu m$   $\sigma_y \sim 15\mu m$ ),  
2 DUTs for timing reference



Efficiency as a function of preamplifier current:



Time resolution as a function of preamplifier current:



Improved efficiency for prototype with gain layer, despite reduction of epitaxial thickness w.r.t. prototype with gain.

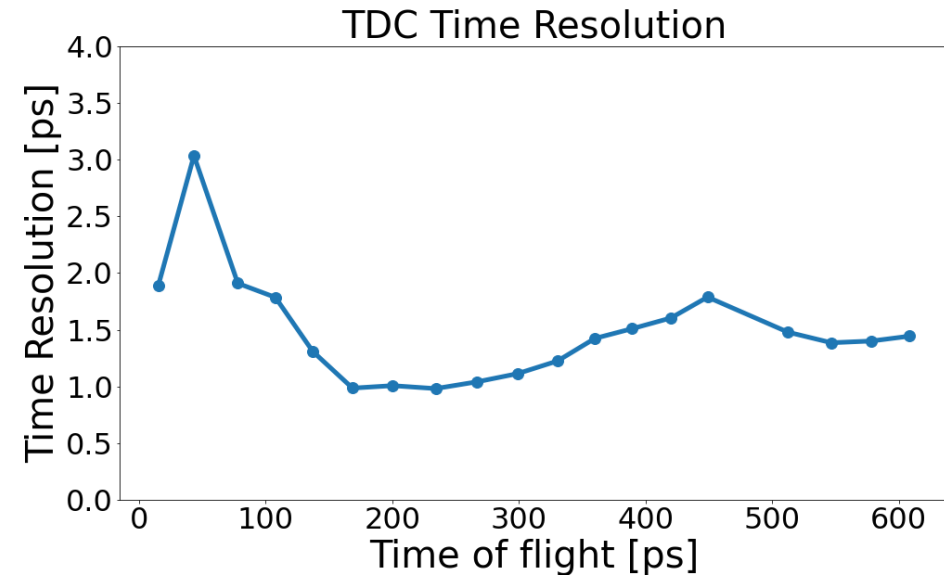
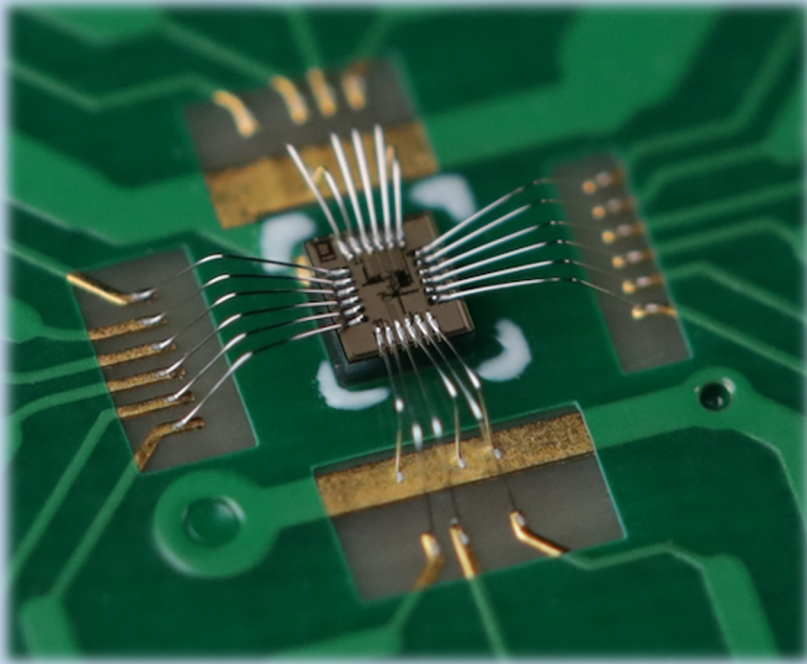
$$\sigma_{\text{PicoAD}p_0} = (24.2 \pm 0.7) \text{ps}$$

→ Proof of concept, not optimized for timing yet.

→ Efficiency > 99.5% and time resolution ~40ps even at low preamplifier current of 20 $\mu\text{A}$ .

# Picosecond TDC

## Picosecond TDC test chip



Integrated in MONOLITH p1 Prototype: under test  
Improved TDC version back from foundry in April 2022.

# Conclusion and outlook

- **Proof of concept of PicoAD sensor + HBT frontend:**
- **> 99.9% efficiency ~25ps time resolution**
  
- **Study of fundamental electron-hole gain processes in multi junction sensor**
  
- **Development of picosecond TDC for fully monolithic MONOLITH chip**
  
- **Development of optimised sensor with TCAD**

**BACKUP**